

Application No.: 09/687,048
Response to Office Action of March 22, 2006
Attorney Docket: AMKOR-052A

AT
SPW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Lee, Tae Heon)	Confirmation No.	1120
)		
Serial No.:	09/687,048)	Art Unit:	2814
)		
Filed:	October 13, 2000)	Examiner:	Nguyen, Dilinh P.
)		
For:	Leadframe and Semiconductor)		
	Package With Improved Solder Joint)		
	Strength)		

RESPONSE TO FINAL OFFICE ACTION UNDER 37 C.F.R. §1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

*off to enter
Dilinh Nguyen*

Dear Sir/Madam:

Applicant hereby responds to the Final Office Action of March 22, 2006 as follows:

Amendment to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.